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(12) **United States Design Patent**  
**Lu et al.**

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(54) **ELECTRONIC COMPONENT HEATSINK ASSEMBLY**

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(52) **U.S. Cl.**  
USPC ..... **D13/179**

(58) **Field of Classification Search**  
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F28F 2250/00; F28F 3/022; F28F  
2215/04; G06F 1/20; F21V 29/80; F21V  
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See application file for complete search history.

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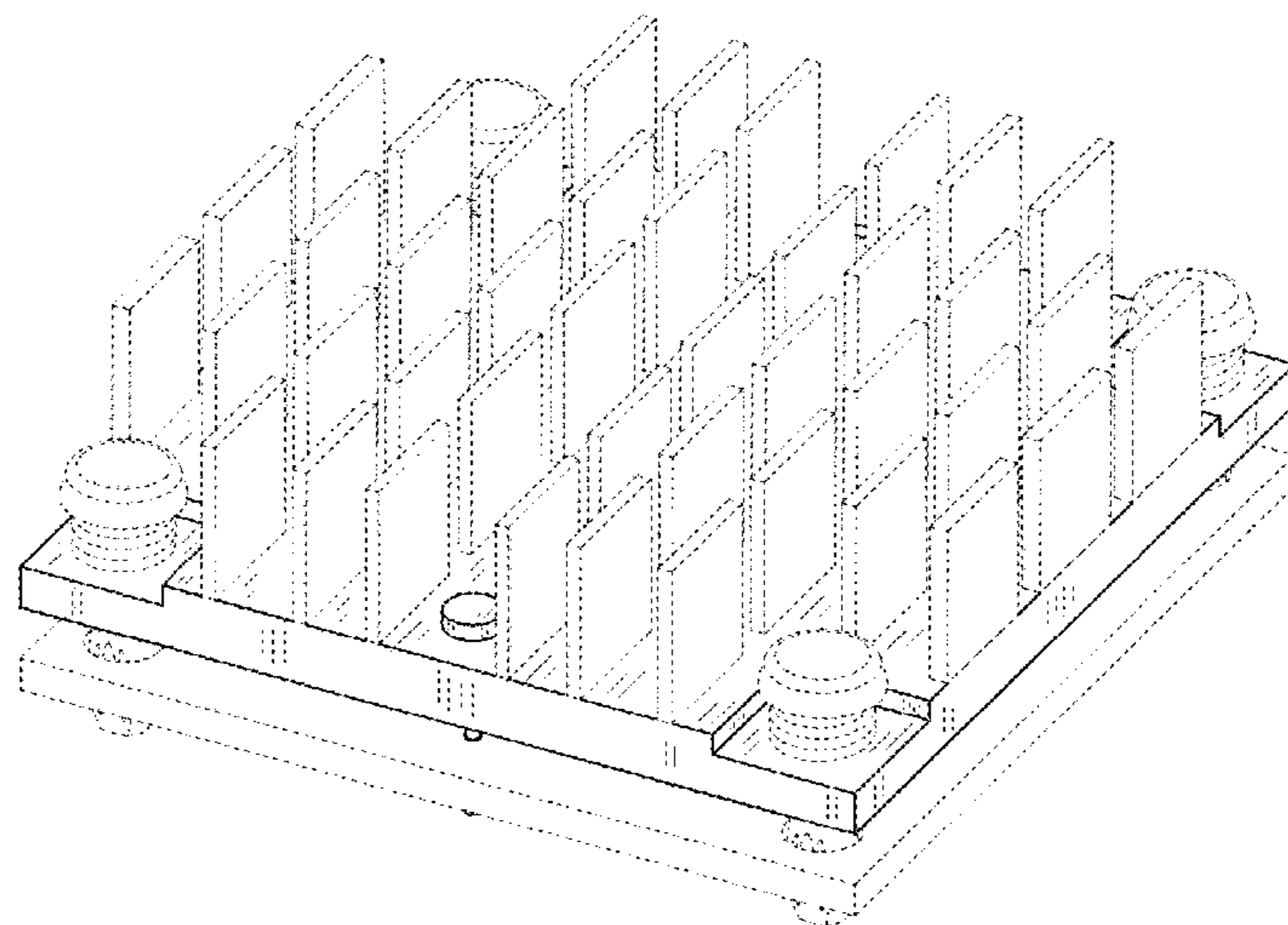
(57) **CLAIM**

The ornamental design for an electronic component heatsink assembly, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of an electronic component heatsink assembly showing our new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a top plan view thereof; FIG. 4 is a right side elevational view thereof; FIG. 5 is a left side elevational view thereof; FIG. 6 is a rear elevational view thereof; and, FIG. 7 is a bottom plan view thereof. The broken lines showing of an electronic component, fins and push pins in the drawings depict environmental subject matter only and form no part of the claimed design.

**1 Claim, 4 Drawing Sheets**



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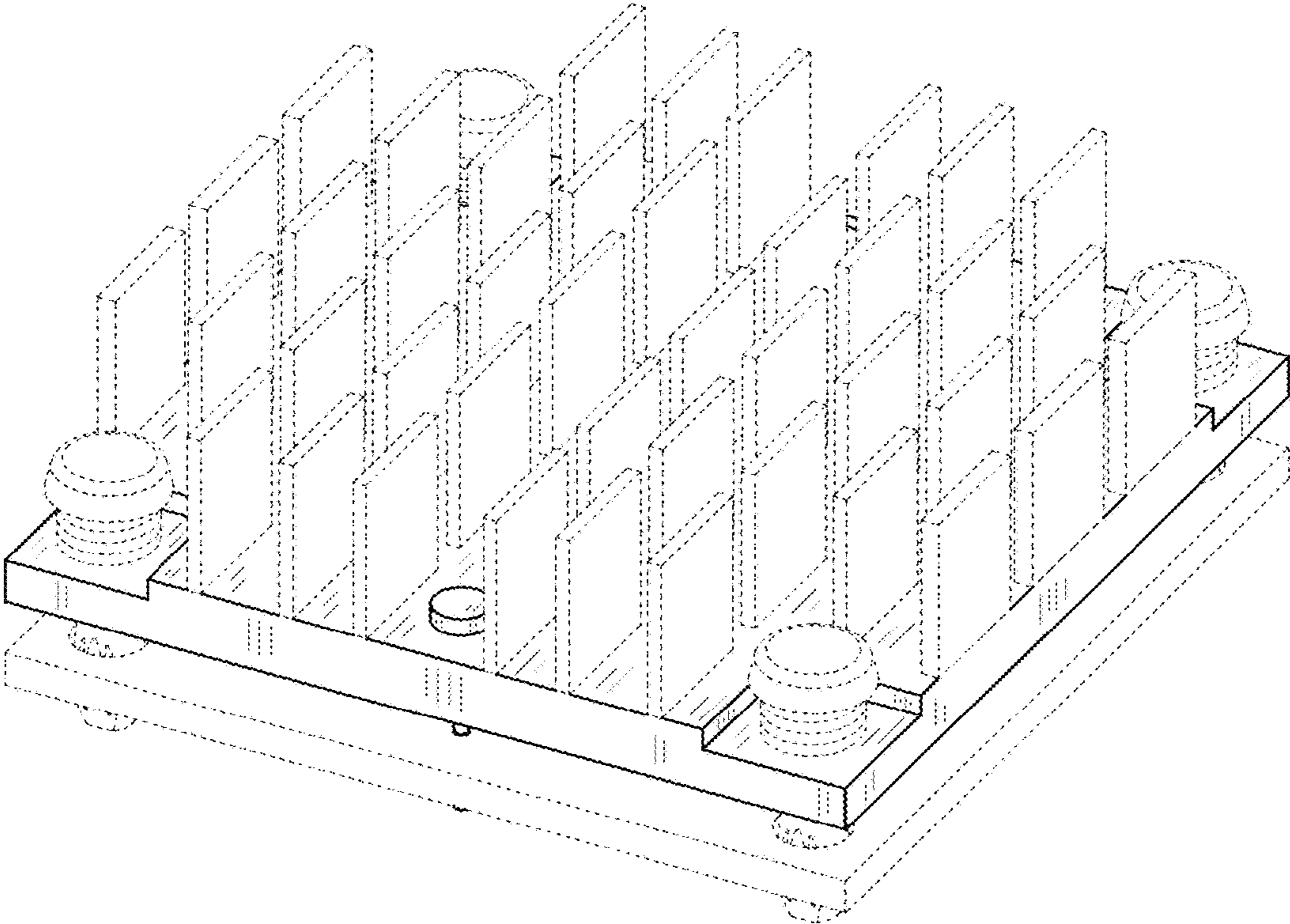


FIG. 1

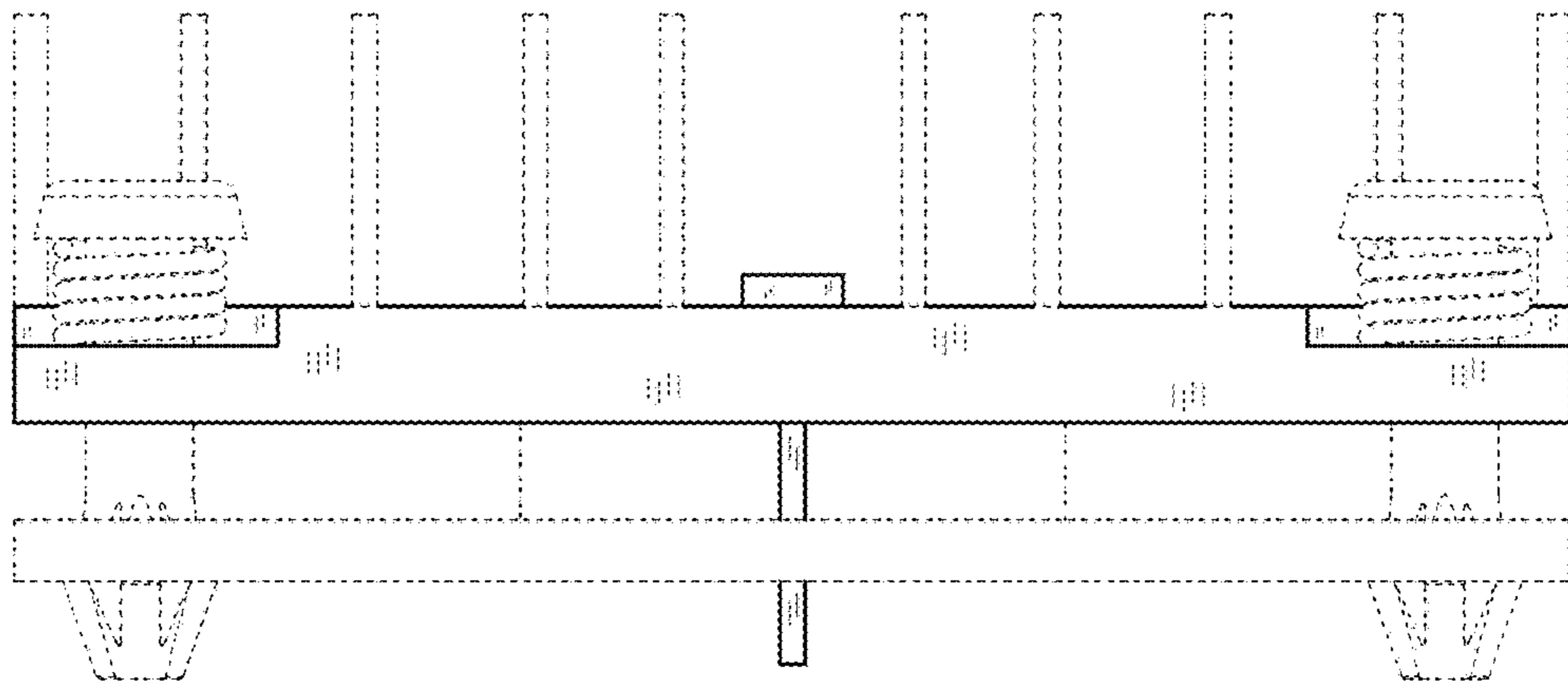


FIG. 2

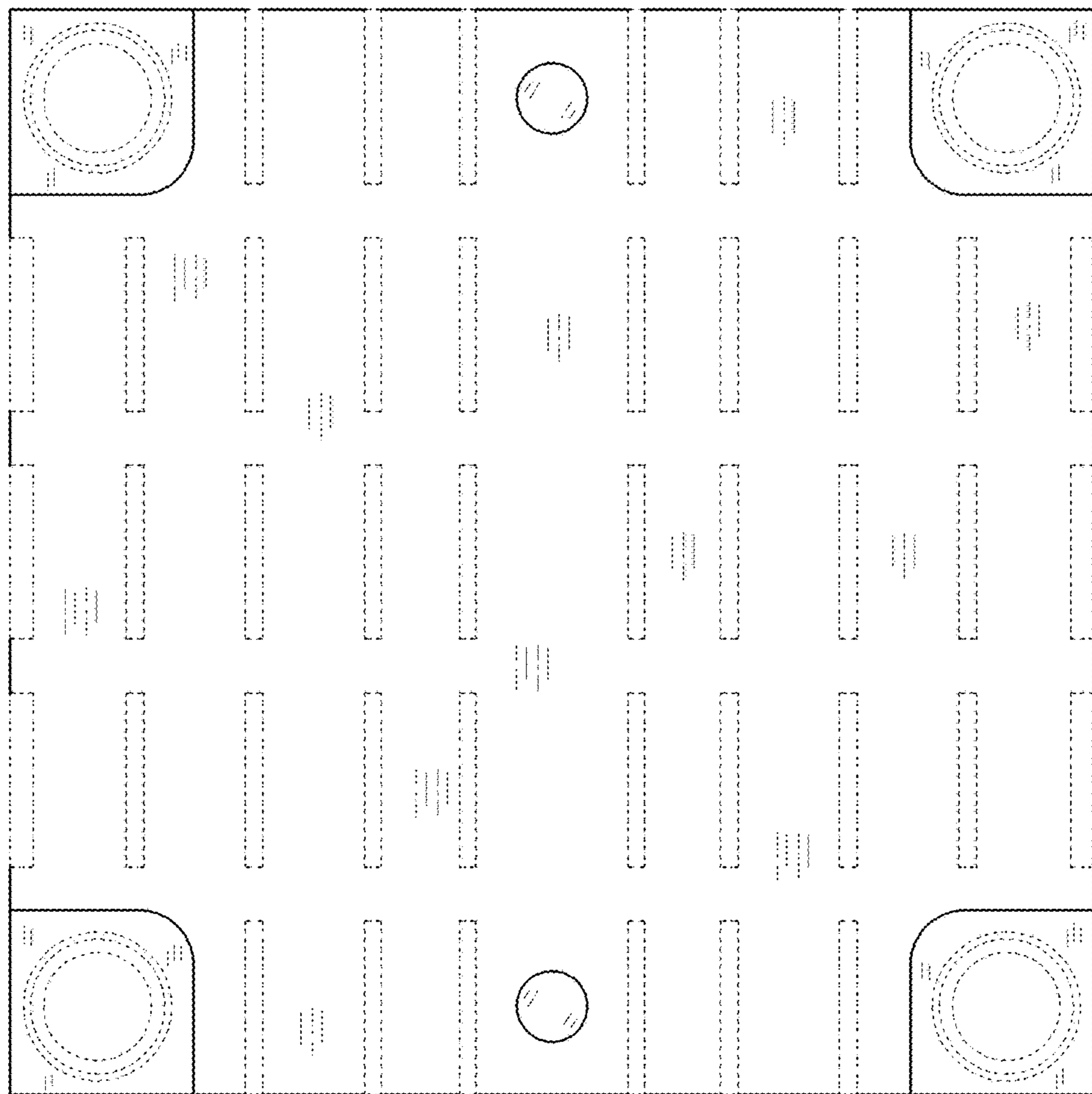


FIG. 3

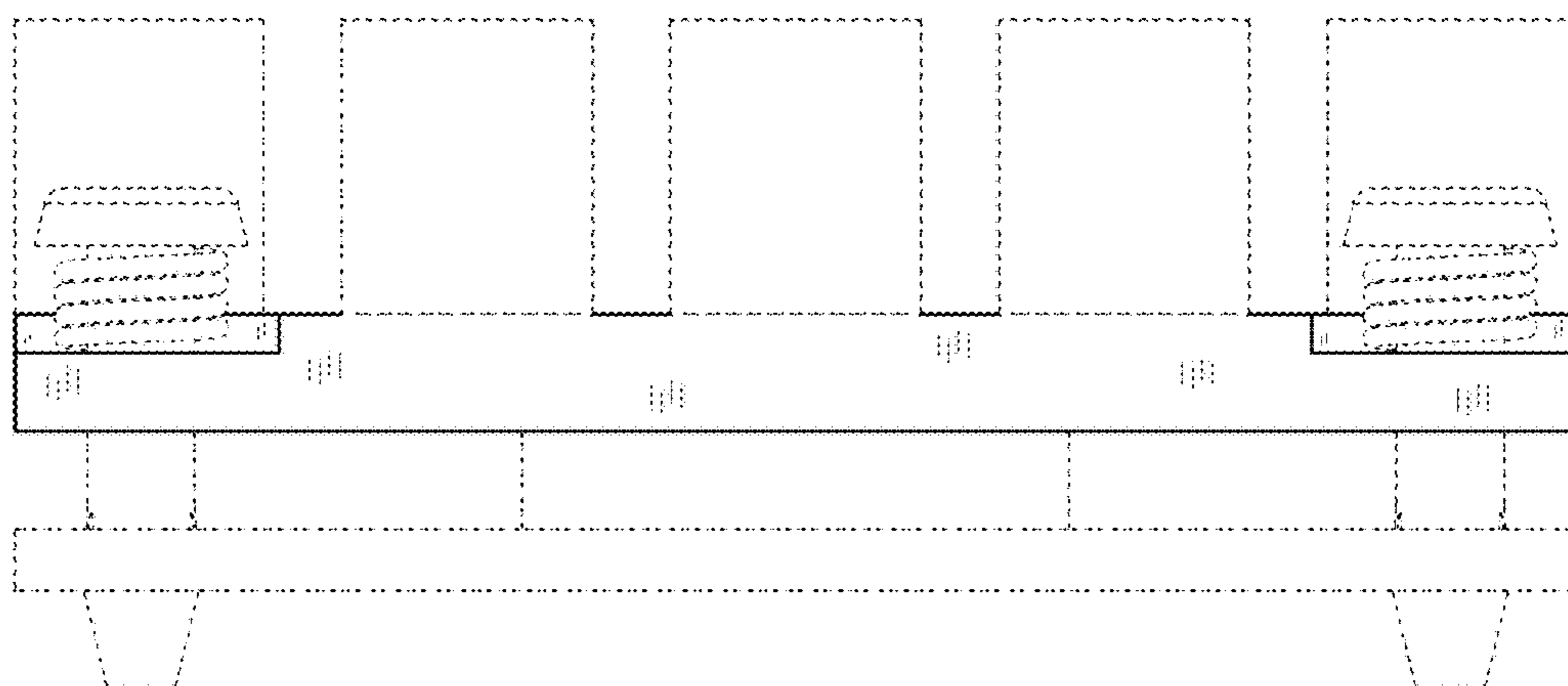


FIG. 4

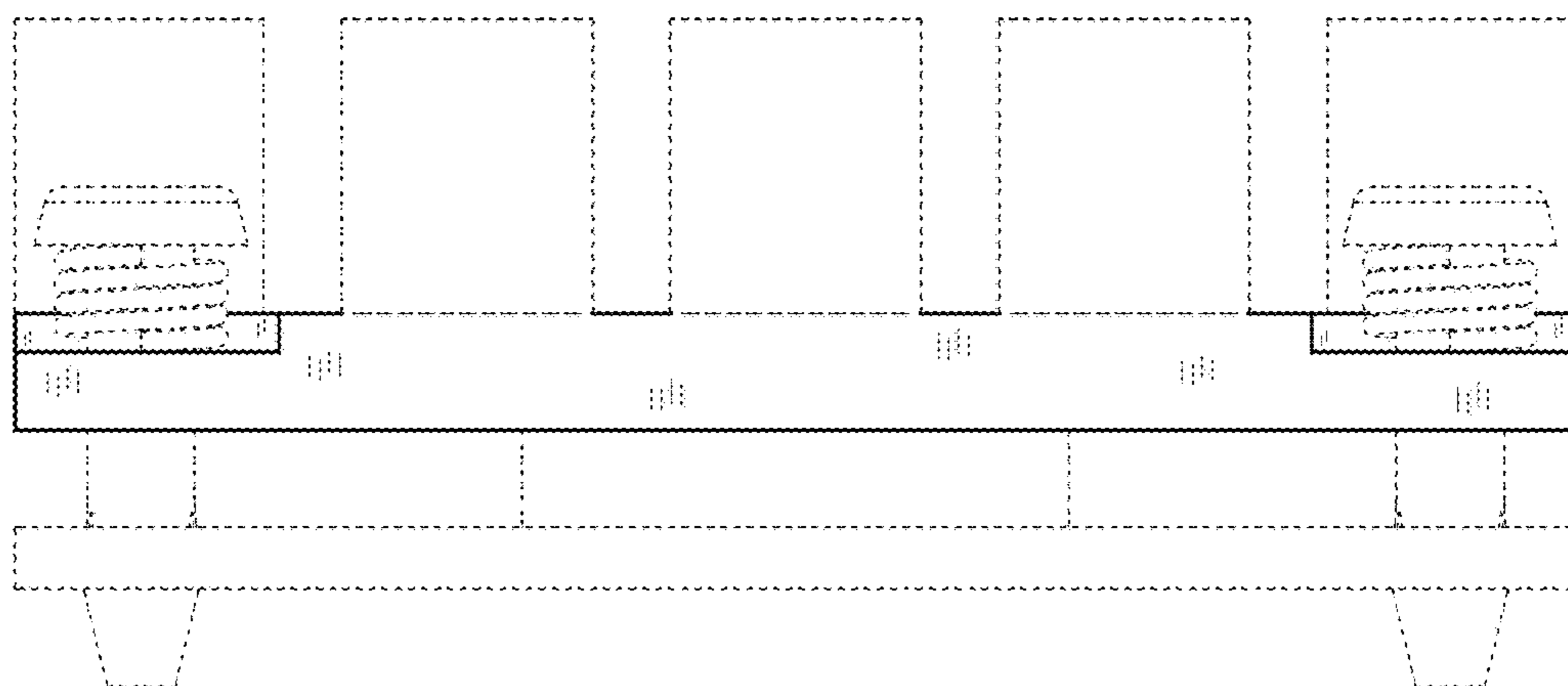


FIG. 5

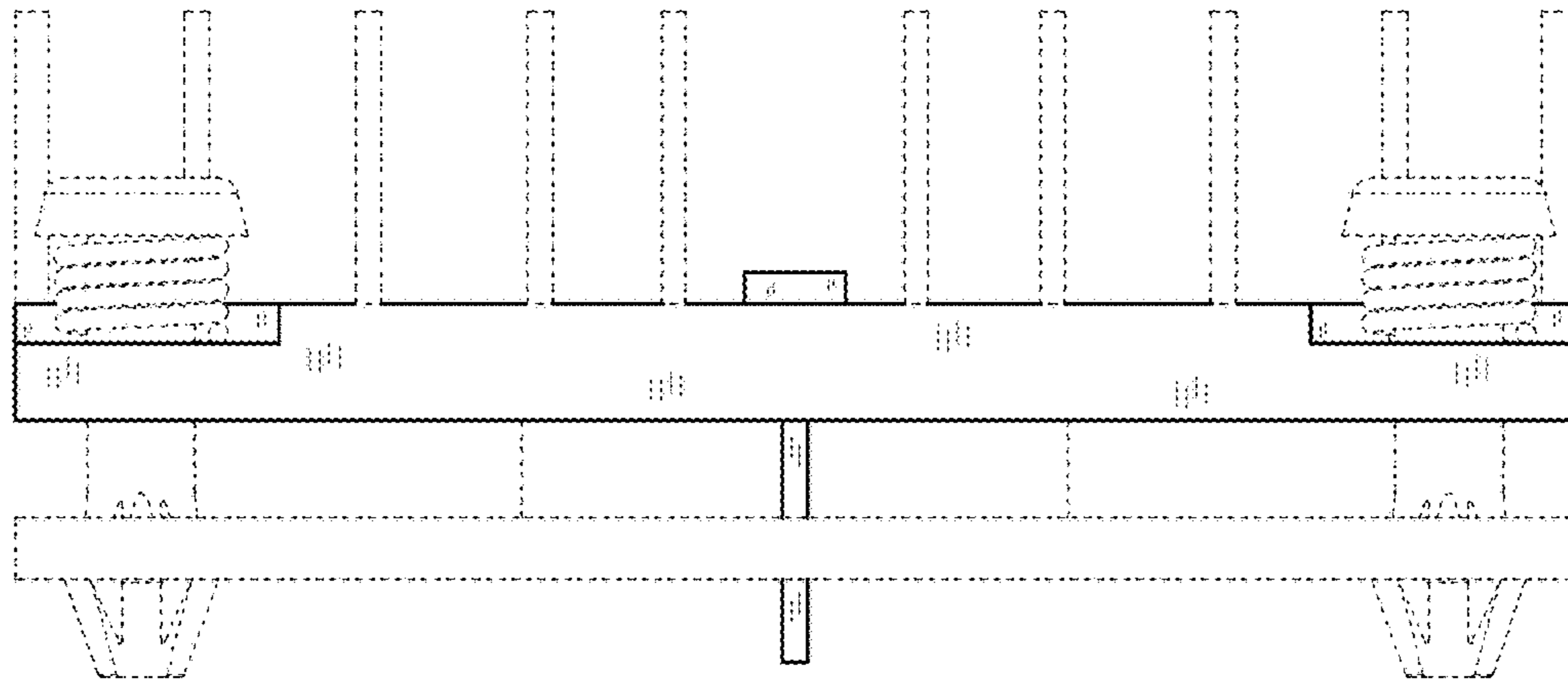


FIG. 6

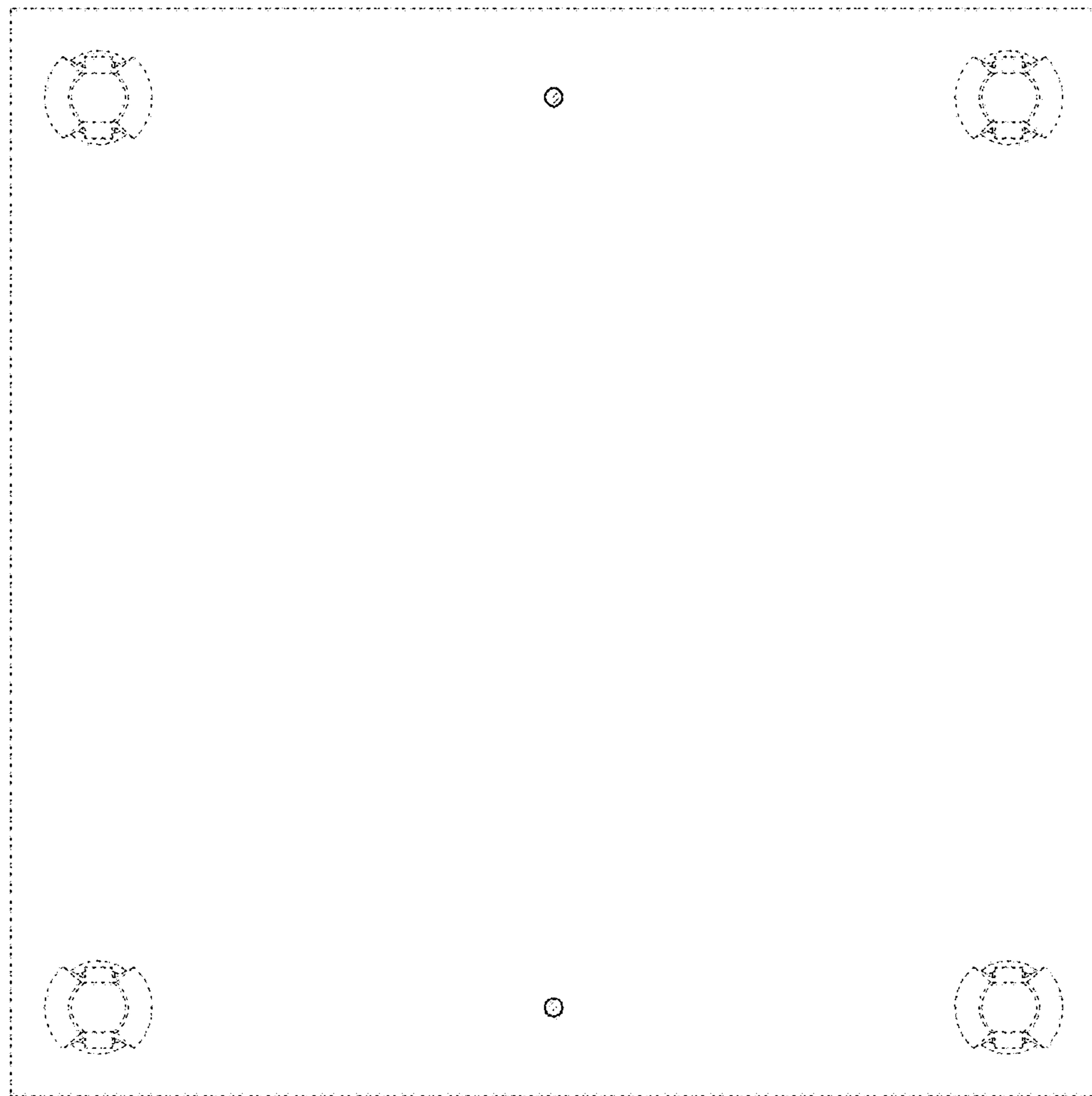


FIG. 7